

Taipei Nangang Exhibition Center, Hall 1 September 13-15, 2017 4th Floor, Booth 908



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TRI will showcase the latest 3D SPI and 3D AOI solutions for SEMICON packaging applications at SEMICON Taiwan 2017. Discover the highest precision inspection at TRI booth **#908!**

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- 4-way DLP Fringe Projection
- 3D Solder Joint Inspection
- Fast CoaXPress Imaging

TR7007Q · 3D SPI

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 Speed and Precision
- Fast CoaXPress Imaging

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